



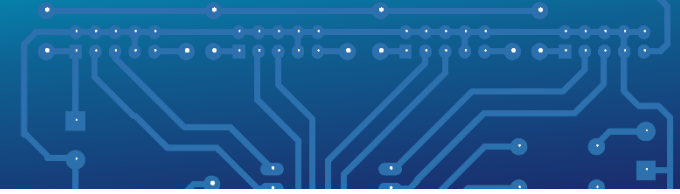
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EEEE2046

Converter PCB Design

Energy Project



- What is a PCB?
- PCB design process and software
- Key considerations for a power converter
 - General layout
 - Track width (and via size)
 - Inductance (and decoupling)



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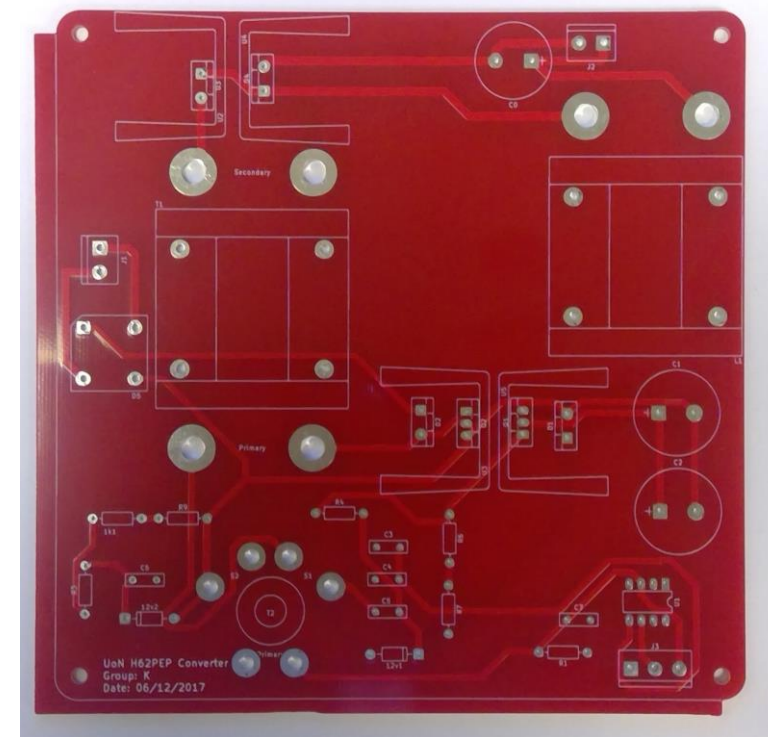
What is a PCB?



What is a PCB?

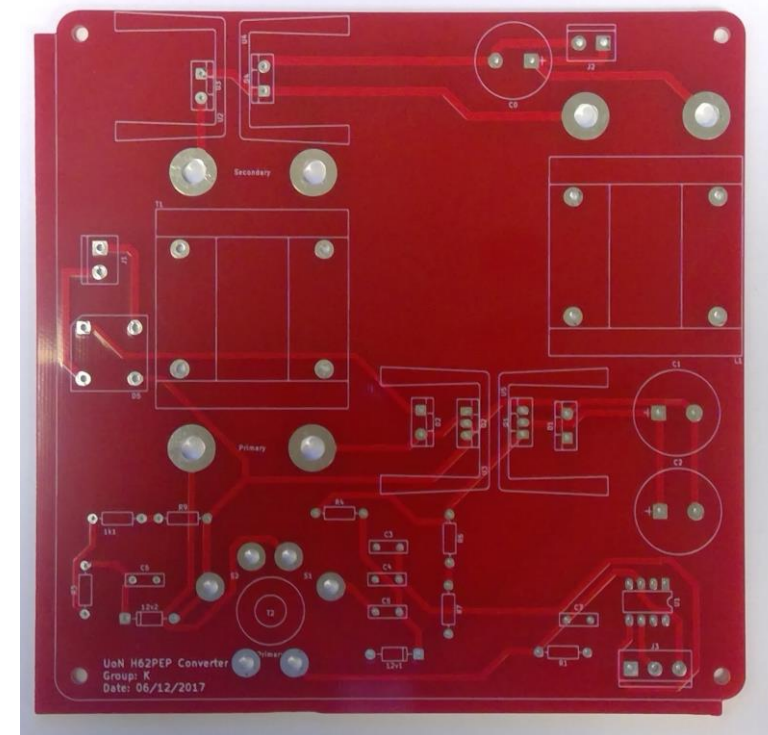
- **Printed Circuit Board**
- Custom designed, manufactured sheet that contains copper tracks to electrically connect components

Why use a PCB?



What is a PCB?

- **Printed Circuit Board**
- Custom designed, manufactured sheet that contains copper tracks to electrically connect components
- **Benefits:**
 - Faster to assemble – can be automated
 - Allows for complex designs – multiple conductive layers
 - Custom pad/hole spacing – SMD, switches, etc.
 - Mechanical support
- **Drawbacks:**
 - Expensive to manufacture – particularly in small quantity
 - Requires specialist design software and skills





What is a PCB?

- Layers – double sided board

Text and symbols

Front Silkscreen

Front Solder Mask

Front Copper

Substrate

Back Copper

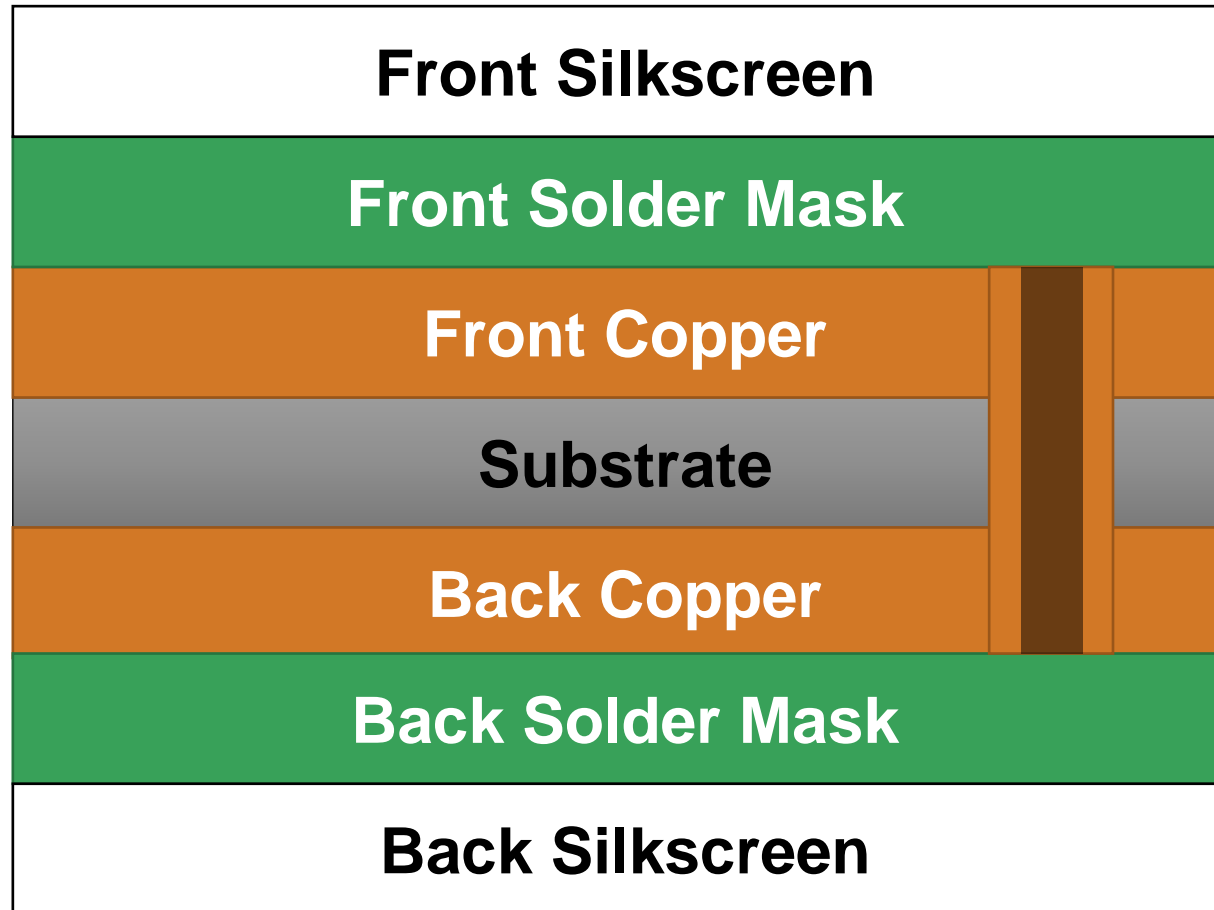
Back Solder Mask

Back Silkscreen

**Colour layer to
protect tracks**

**Conductive
layers for tracks
and pads – can
join with vias**

Fibreglass (FR4)

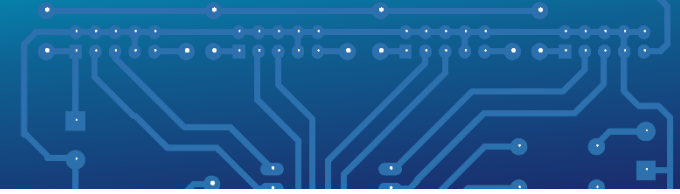




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Design process



- Lots of packages available for PCB design

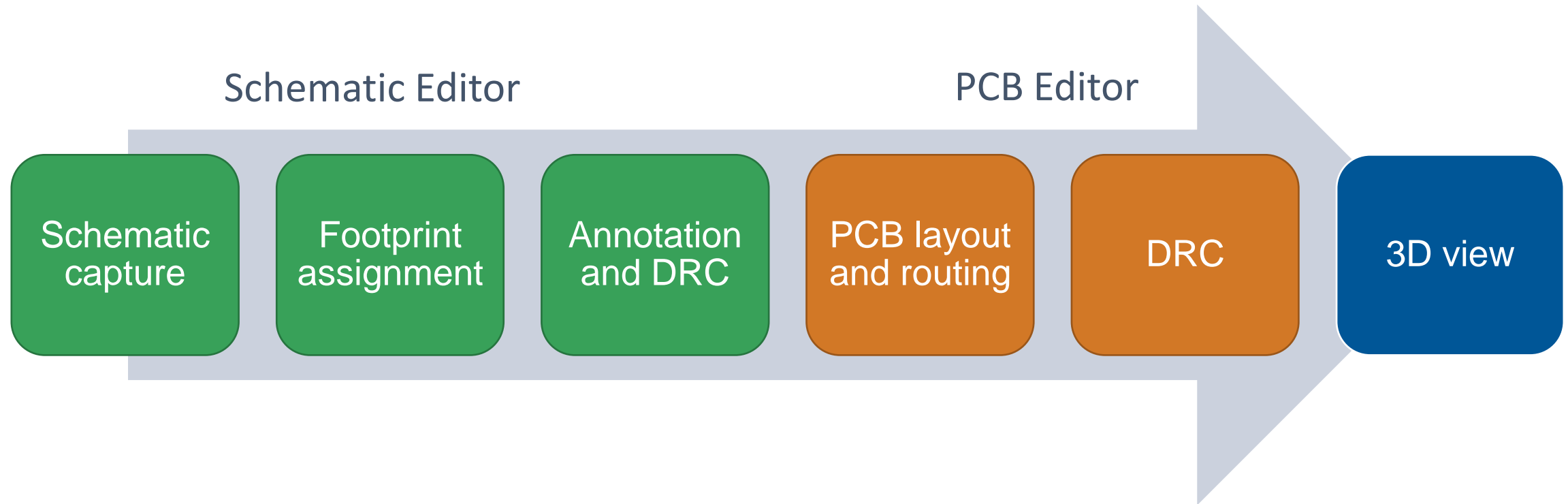
- We will use **KiCAD**

- Free and open source – no licence required, no board limitations
- Compatible with Windows, Linux, and Mac

- Available at: <http://kicad.org/download/>

- Pre-installed on the lab PCs and in the tower computer room





DRC = Design Rule Check



Schematic capture

Footprint assignment

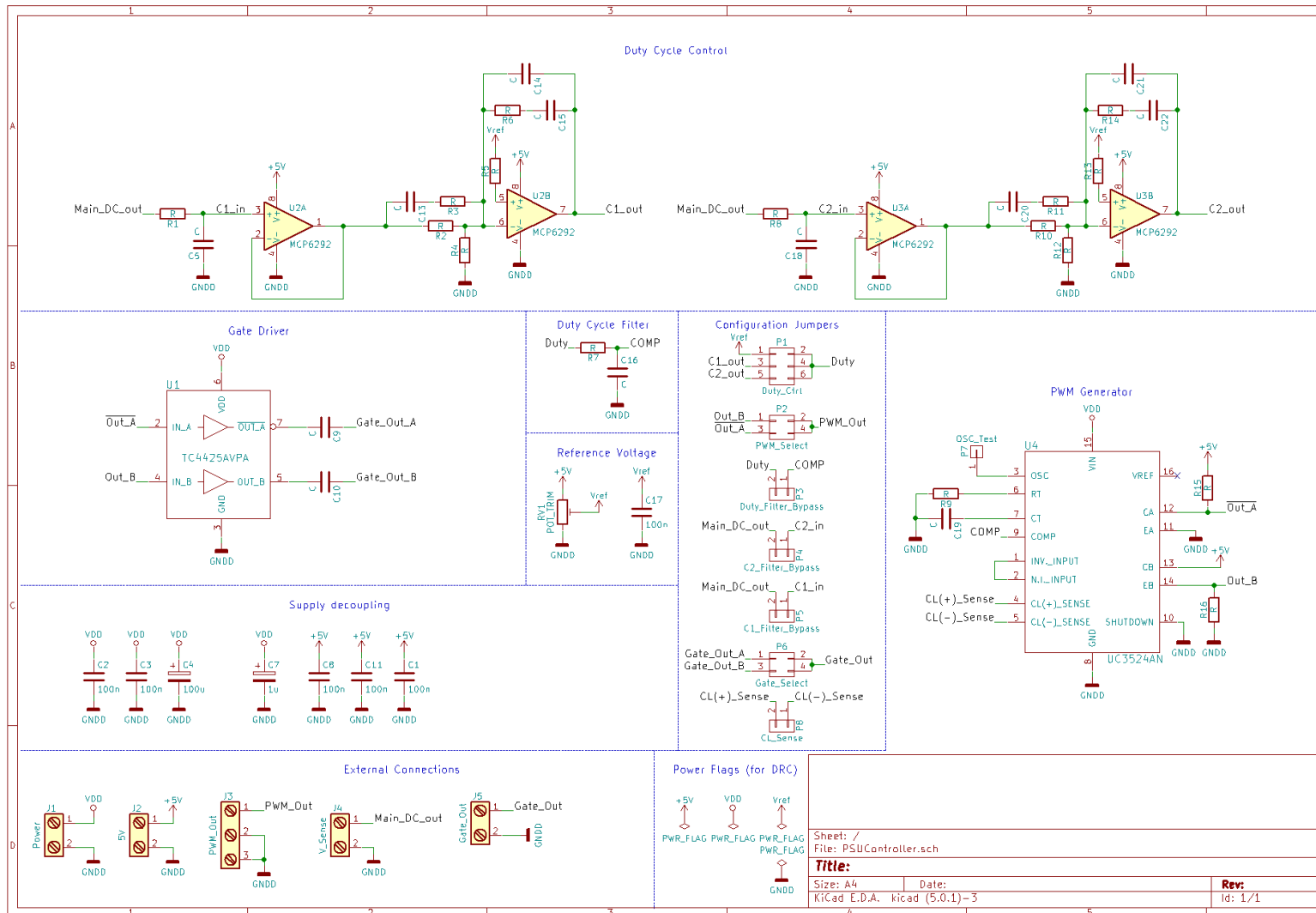
Annotation, DRC, Netlist

PCB layout and routing

DRC

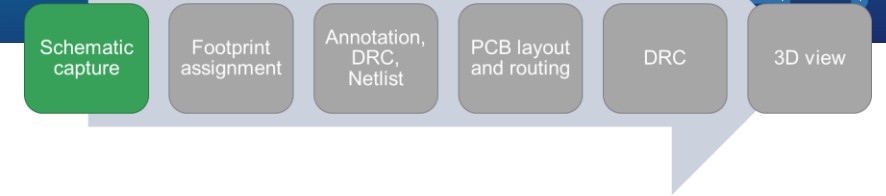
3D view

• Schematic Capture:



If starting from scratch you would need to draw a schematic.

For the PCB coursework the template includes the schematic. (not this one)



- **Through schematic capture you can:**

- Place component symbols
- Connect with wires – you can also use labels
- Add 'PWR_FLAG' symbols – these indicate external power sources

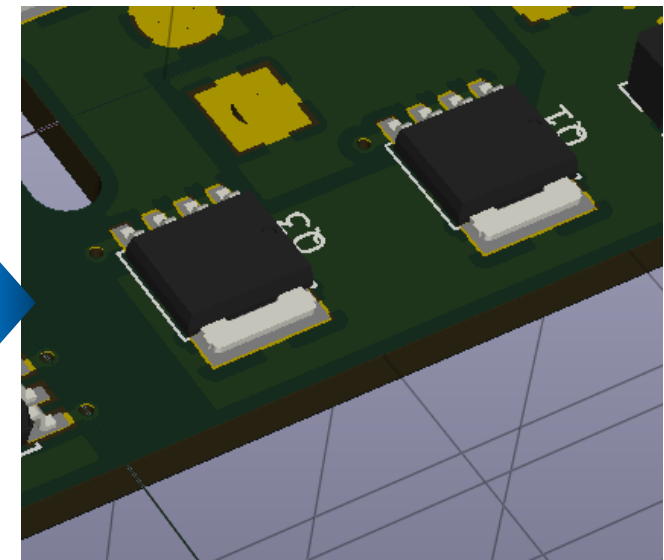
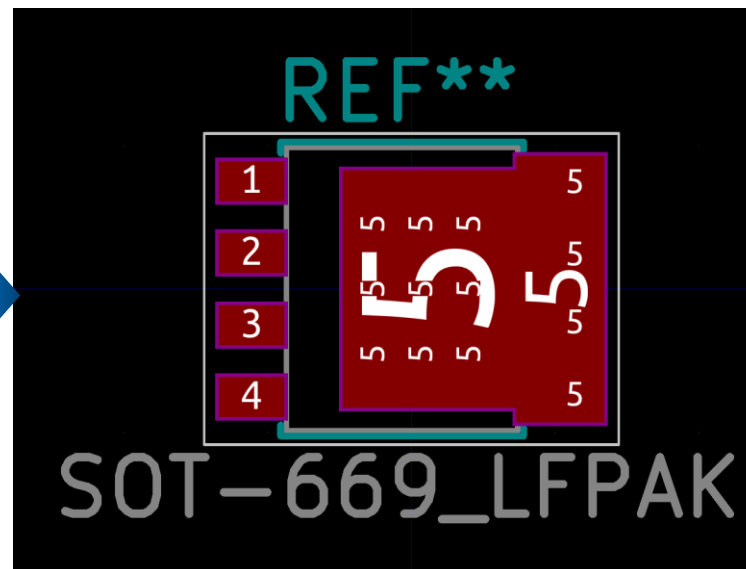
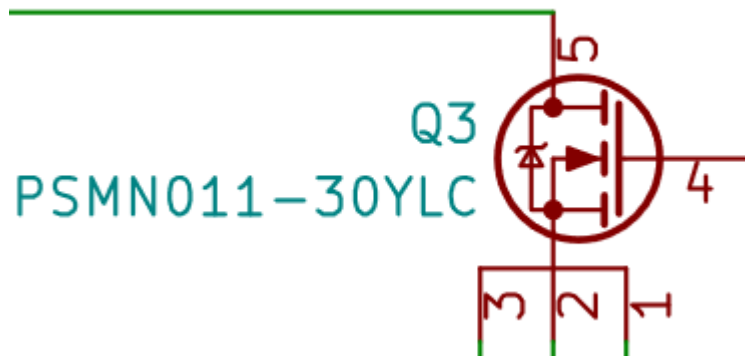
Power Flags (for DRC)

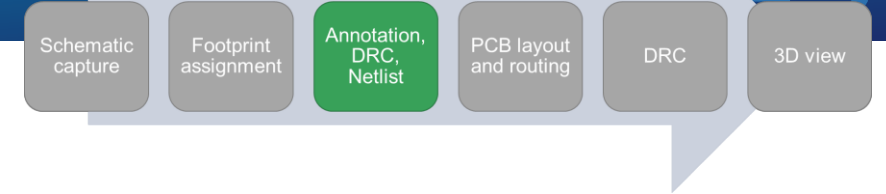


- Make sure to keep the layout neat – you'll rely on the schematic when debugging

• Component/Footprint selection:

- Need to link the schematic symbol to a physical layout of pads (called a footprint)
- Must match the component you plan to use – you can confirm this by taking measurements from the part, or checking the datasheet
- We've produced a custom library as part of the template that includes footprints for the project





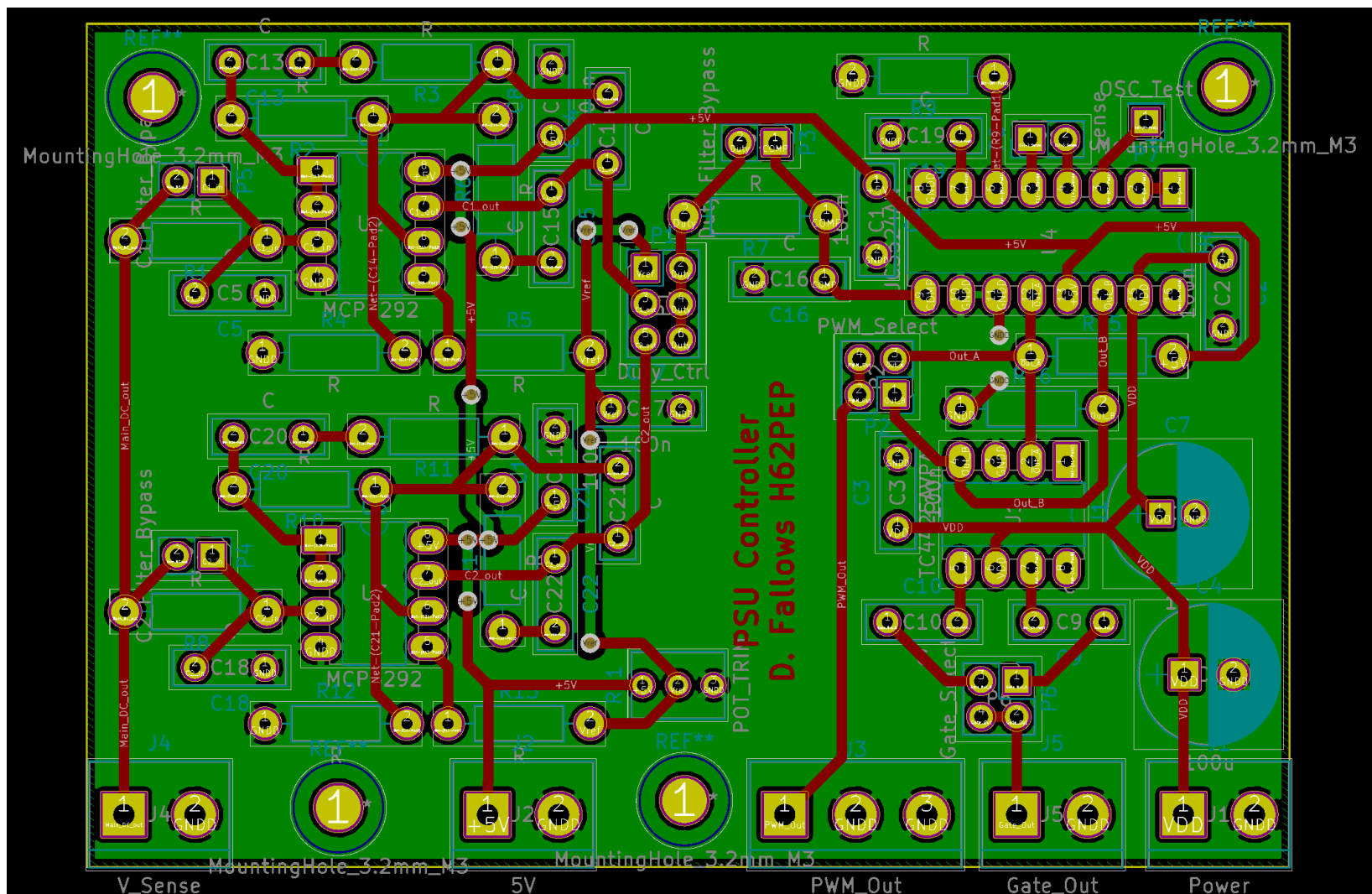
- **Annotation and DRC:**

- Annotation assigns each component a unique letter/number combination
- Design Rule Check (DRC)
 - Checks the schematic for simple errors (e.g. unconnected pins)
 - Does not check functionality – passing DRC **does not** mean your circuit will work



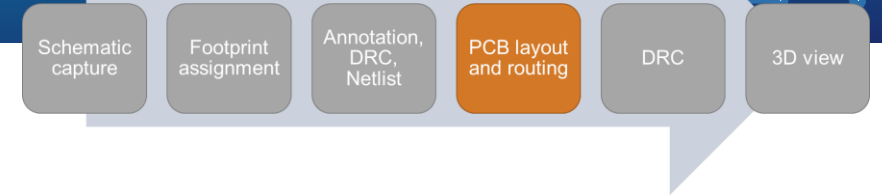
- [In old versions of KiCAD you have to manually generate the netlist. Since version 6 this is now automatic].

• PCB Layout:



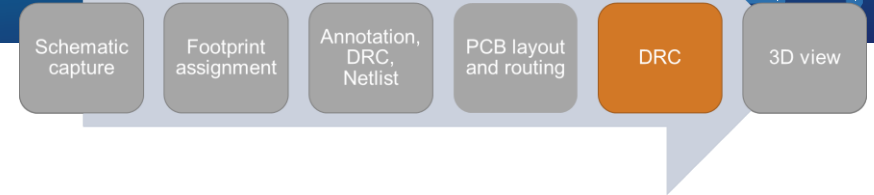
This is what you need to produce – but for the main converter schematic.

(This is the control board you'll be given in a later project week).



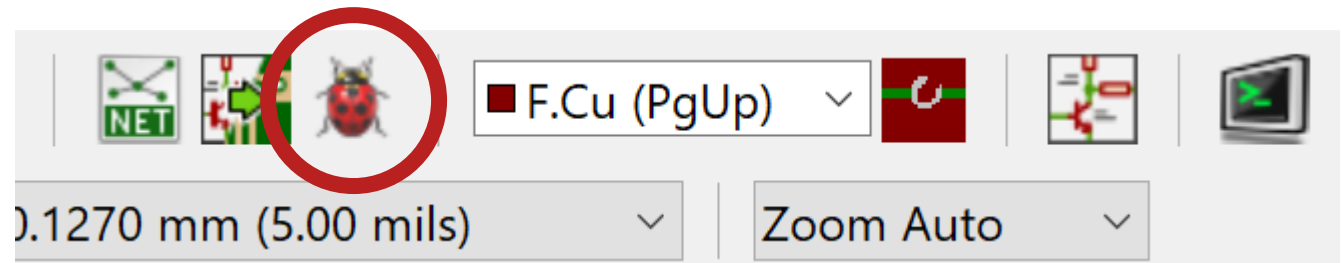
- **Basic PCB layout tips:**

- Think about component placement
 - Will it be easy to solder? Are connectors accessible? Can test leads be easily fitted?
 - Are connected signals close by – minimise track lengths
- Use both layers
 - For tracks and components
 - Use fill planes where possible (e.g. GND, V+)
- Label components, connectors, signals
 - Makes it easier to construct and debug
 - Can also add test points for key signals



- **PCB DRC:**

- Performs key checks
 - Are tracks too close
 - Are all the connections made
 - Are components overlapping
- Does **not** confirm the design is good or will work



Schematic
capture

Footprint
assignment

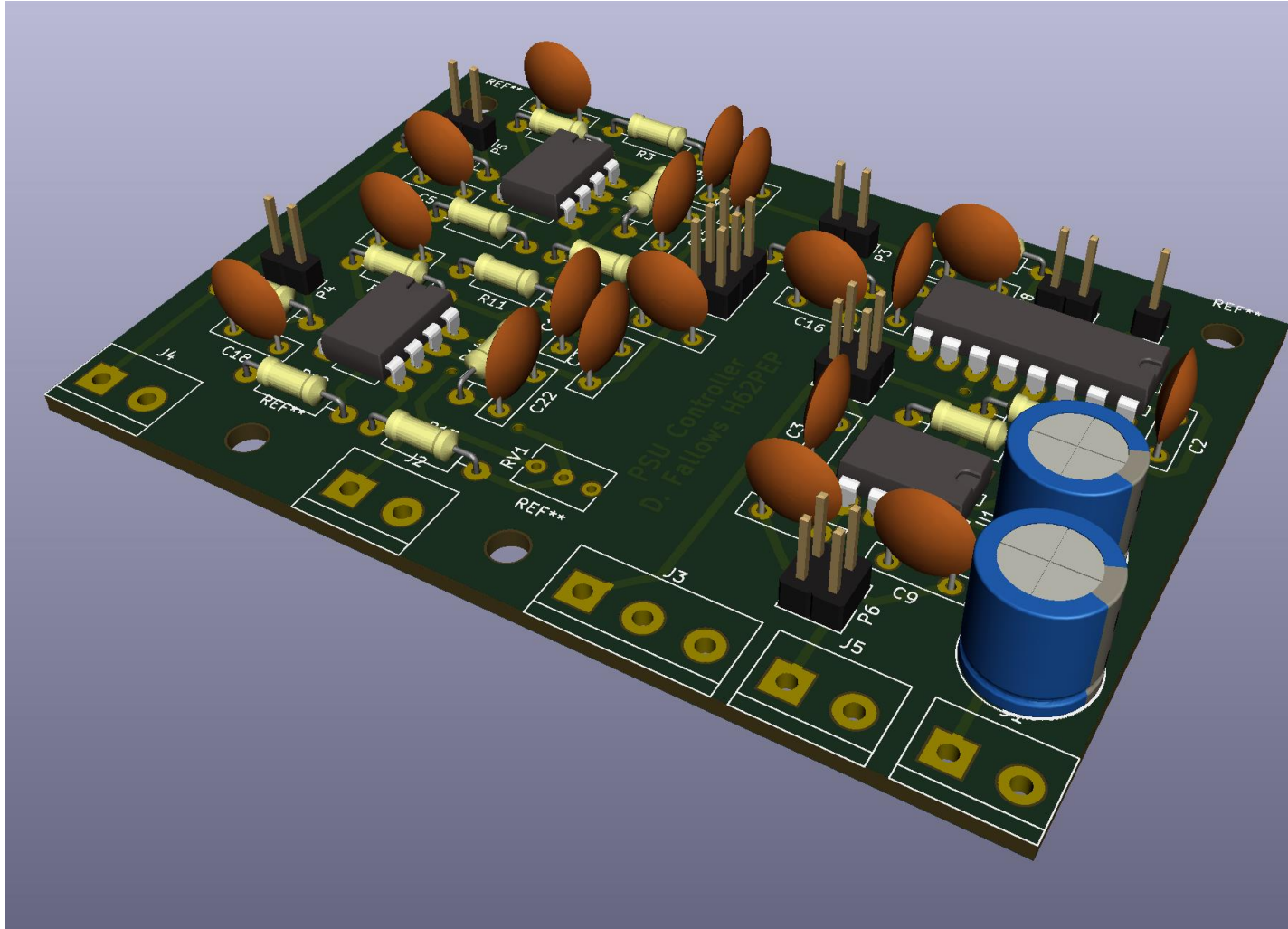
Annotation,
DRC,
Netlist

PCB layout
and routing

DRC

3D view

- 3D Rendering:



The 3D viewer (Alt+3)
will give a rendering
of your design.

This can be helpful to
check if it can be built
and used easily.
(Also useful to see
any silkscreen
mistakes)



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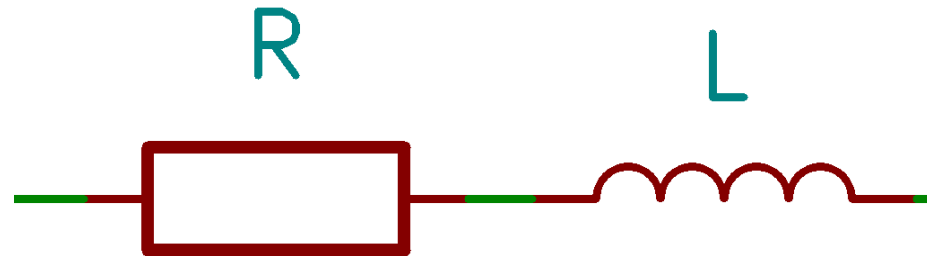
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Power Electronic Considerations



Key Considerations

- **Power converters combine high current with high frequency:**
 - Must be considered when designing the PCB
 - Copper tracks are not perfect conductors
 - Resistance will generate heat
 - Inductance will filter high frequencies





Key Considerations

- **Resistance is controlled by track width**
 - Wider track = more copper area = lower resistance
 - (just like the wire calculation for your wound components)
- KiCAD calculator for minimum track width
 - Need to know the current and choose a suitable temperature rise
- If using vias these must also be a suitable size
 - (and/or use multiple in parallel)

PCB Calculator

Regulators | **Track Width** | Electrical Spacing | TransLine | RF Attenuators | Color Code | Board Classes

Parameters:

Current: **3** A

Temperature rise: 60 deg C

Conductor length: 20 mm

Resistivity: 1.72e-8 Ohm-meter

If you specify the maximum current, then the trace widths will be calculated to suit.
If you specify one of the trace widths, the maximum current it can handle will be calculated. The width for the other trace to also handle this current will then be calculated.
The controlling value is shown in bold.

The calculations are valid for currents up to 35A (external) or 17.5A (internal), temperature rises up to 100 deg C, and widths of up to 400mil (10mm).
The formula, from IPC 2221, is
$$I = K * dT^{0.44} * (W*H)^{0.725}$$

where:
I = maximum current in amps
dT = temperature rise above ambient in deg C
W,H = width and thickness in mils
K = 0.024 for internal traces or 0.048 for external traces

External layer traces:

Trace width: **0.460809** mm

Trace thickness: 0.035 mm

Cross-section area: 0.0161283 mm x mm

Resistance: 0.0213289 Ω

Voltage drop: 0.0639868 Volt

Power loss: 0.19196 Watt

Internal layer traces:

Trace width: **1.19877** mm

Trace thickness: 0.035 mm

Cross-section area: 0.0419569 mm x mm

Resistance: 0.00819889 Ω

Voltage drop: 0.0245967 Volt

Power loss: 0.07379 Watt



Key Considerations

- **Inductance** is controlled by track length and width
 - Short track = lower inductance, Wide track = lower inductance
- Think about effect of additional inductance on each circuit connection
 - Is there already significant inductance present?
 - Is the connection carrying high frequency current?

Flat Wire Inductor Calculator

The inductance of a flat or ribbon wire (rectangular cross section), can be found using the calculator or the equation given below.

INPUT DATA		
Length:	<input type="text" value="20.0"/>	cm
Width:	<input type="text" value="0.3"/>	cm
Thickness:	<input type="text" value="0.035"/>	mm

RESULTS	
Inductance:	<input type="text"/> nH

<https://chemandy.com/calculators/flat-wire-inductor-calculator.htm>



Key Considerations

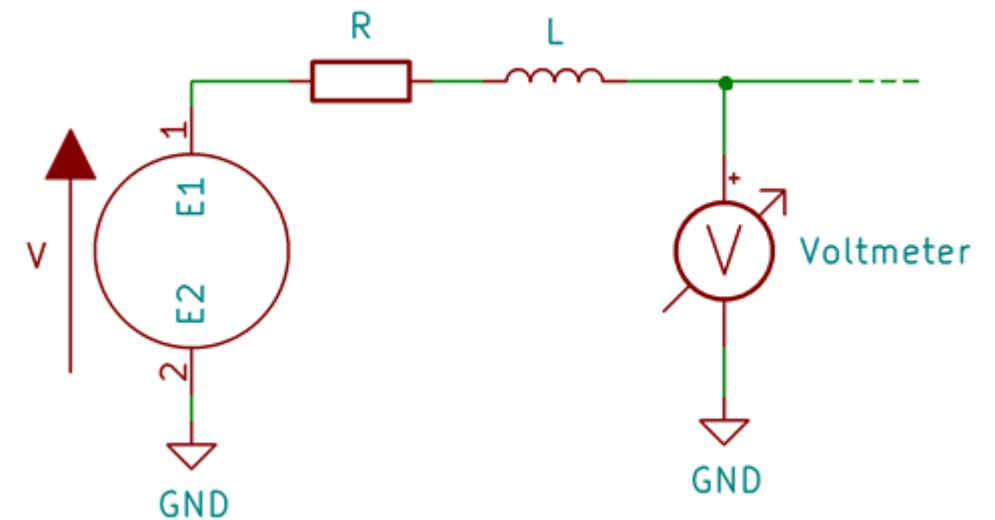
- **Decoupling (and the gate driver)**

- Power is supplied through a track
 - Voltage drop across R due to current flow (ohms law)
 - Voltage ripple across L due to change in current

- Voltmeter reading \neq supply voltage

- Need to consider the connected load

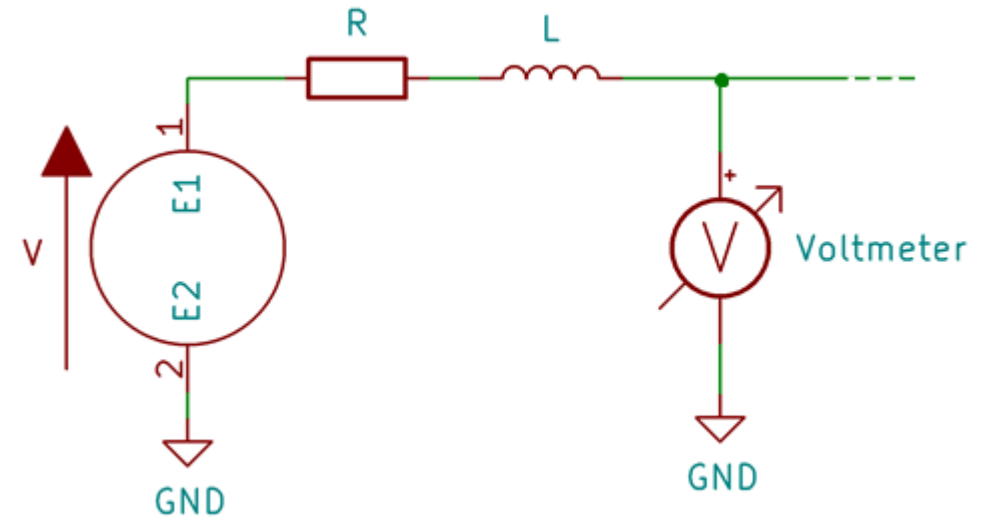
- Does it draw a constant current?
- If not, voltage ripple may be significant and cause malfunction
- May exceed the supply voltage \rightarrow component damage
- May drop low causing the device to turn off or reset





Key Considerations

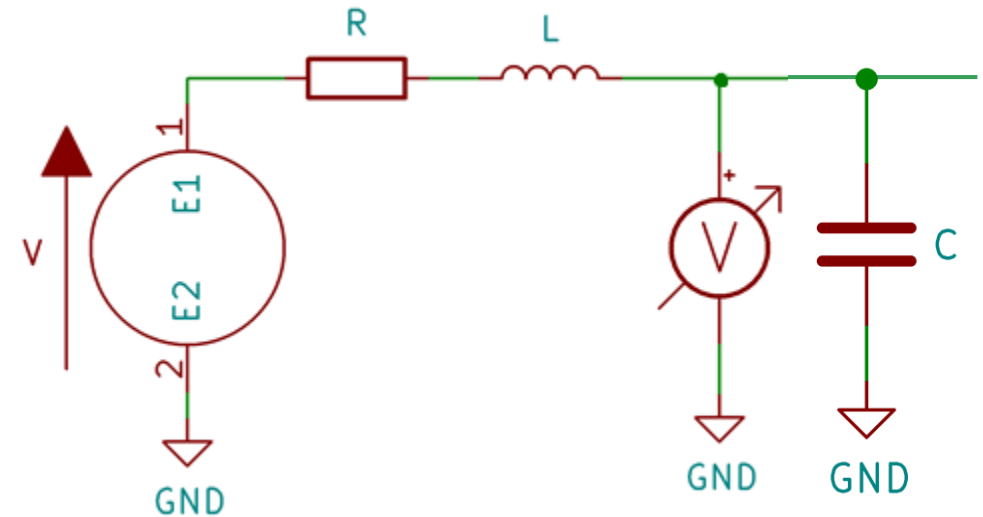
- **Decoupling** (and the gate driver)
 - Solution?





Key Considerations

- **Decoupling** (and the gate driver)
 - Solution?
 - Smooth ripple by placing capacitor close to the load
 - This provides a low inductance source for high frequency current
- Why is the gate driver sensitive?
 - Draws large, high frequency switching current
 - ~100kHz
 - Rated for up to 3A (datasheet)
 - Inductance will cause large ripple
 - Decoupling must be present



Voltage ripple causes the gate driver to switch on/off quickly, switching loss then heats up the IC.

- **Heatsink placement**

- Although switch-mode power supplies are very efficient, their high power capabilities means produced heat must be managed
 - You'll carry out calculations for this in the lab
 - And measure with the thermal camera
- Heat sinks increase surface area allowing heat to be conducted into the air.
 - Don't block the fins – air flow is required.
 - Consider the size and access
 - Must be screwed to the device
 - Is there room for a screwdriver?
 - Is there clearance for other components

